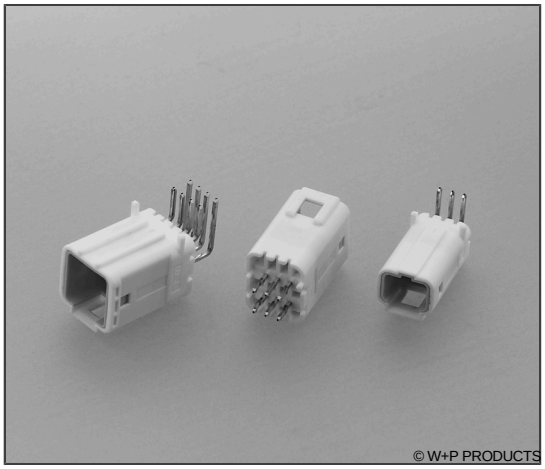
W521

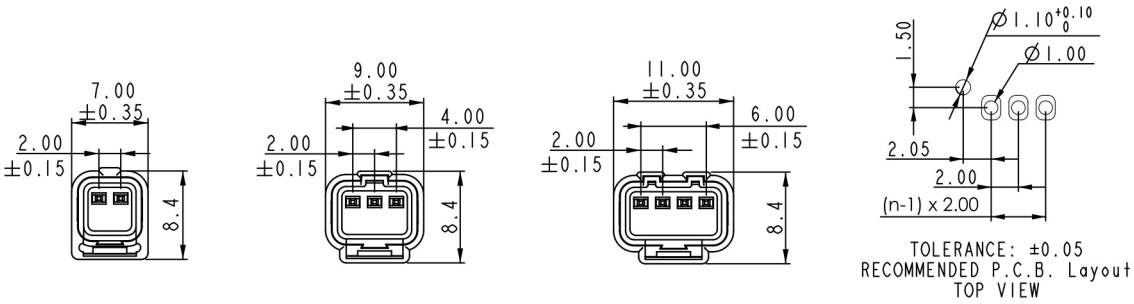
Wire-To-Board Steckverbinder RM 2mm - Waterproof IP67

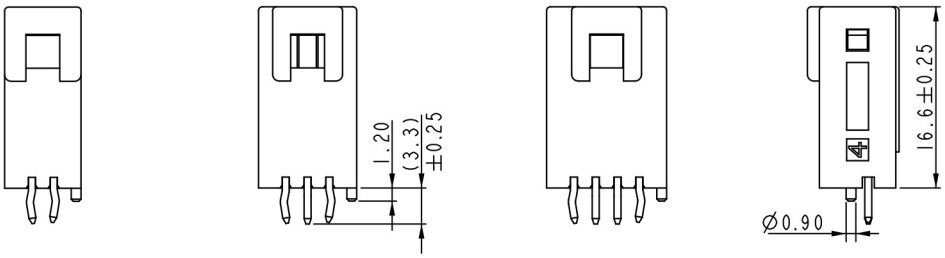
Wire-To-Board Connectors 2mm Pitch - Waterproof IP67

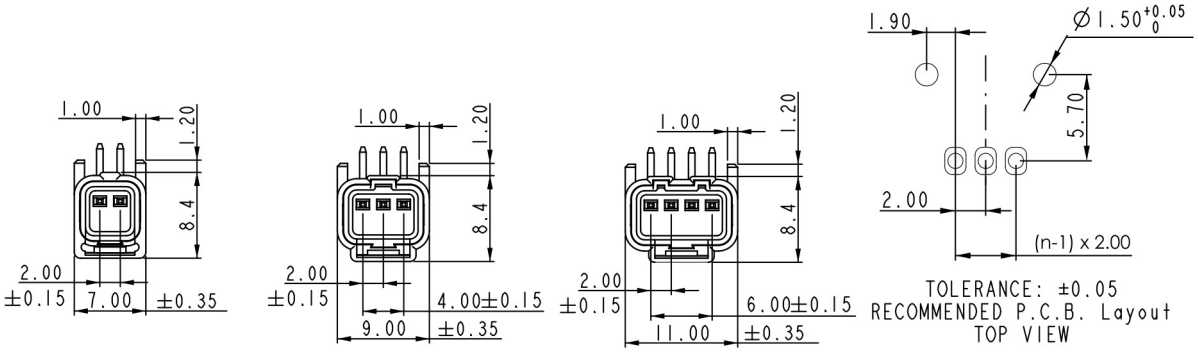
Technische Daten / *Technical Data*

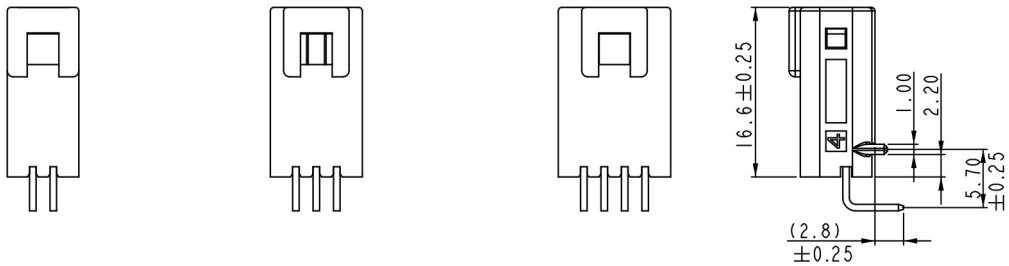
Isolierkörper	Thermoplast, nach UL94 V-0
Insulator	*Thermoplastic, rated UL94 V-0*
Kontaktmaterial	Kupferlegierung, 0,64mm Vierkantstift
Contact Material	*Copper alloy, 0.64mm square pin*
Kontaktoberfläche	Lt. Oberflächenoptionen, über Ni
Contact Surface	*Acc. to options, over Ni*
Durchgangswiderstand	< 20 mΩ
Contact Resistance	*< 20 mΩ*
Isolationswiderstand	> 1000 MΩ
Insulation Resistance	*> 1000 MΩ*
Spannungsfestigkeit	1000 V AC
Test Voltage	*1000 V AC*
Nennspannung	100 V AC/DC
Voltage Rating	*100 V AC/DC*
Nennstrom	4 A
Current Rating	*4 A*
Temperaturbereich	-55 °C ... +85 °C
Temperature Range	*-55 °C ... +85 °C*
Verarbeitung	Wellenlötverfahren
Processing	*Wave soldering*











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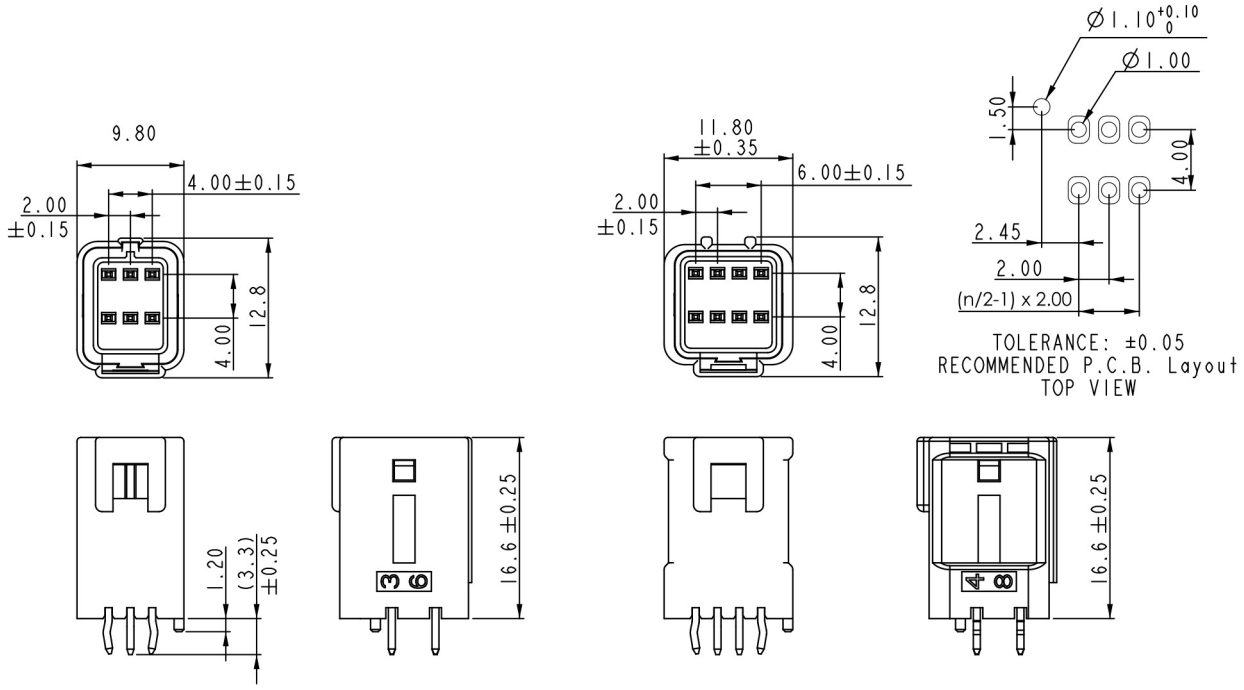
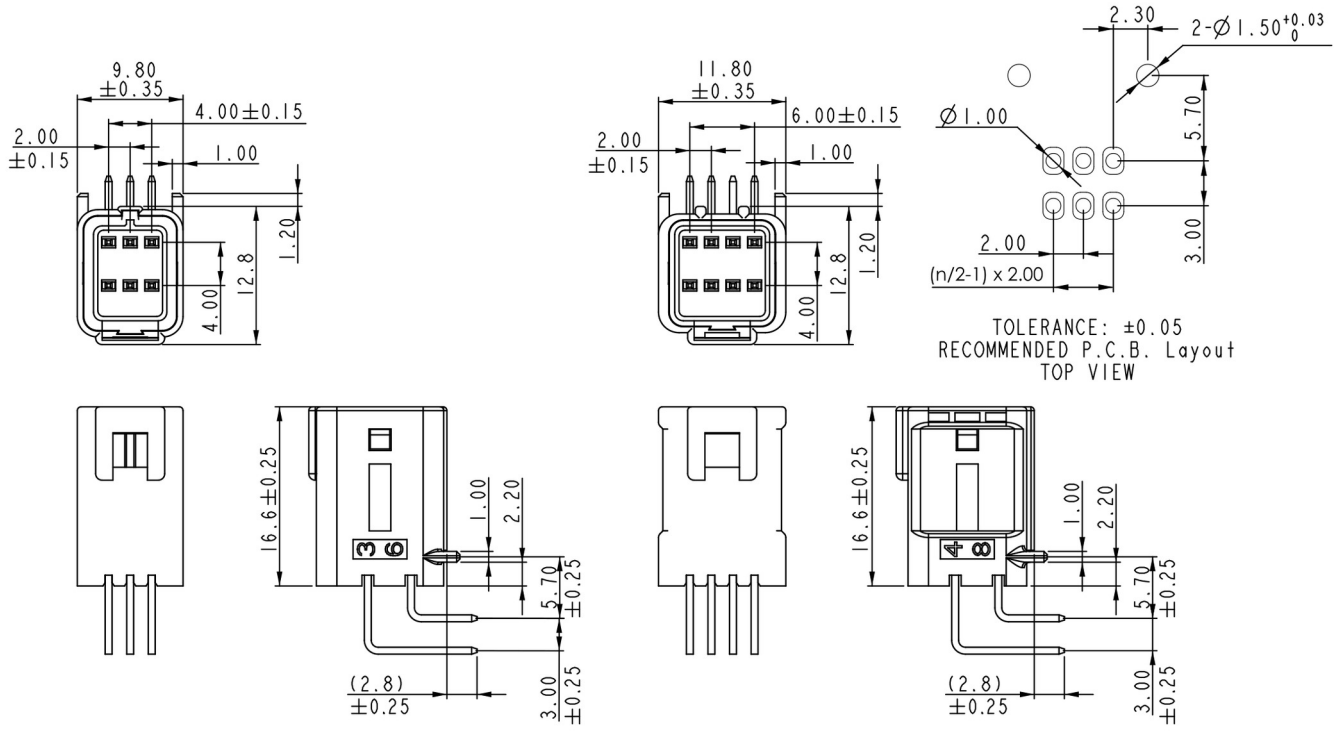
Wire-To-Board Connectors 2mm Pitch - Waterproof IP67



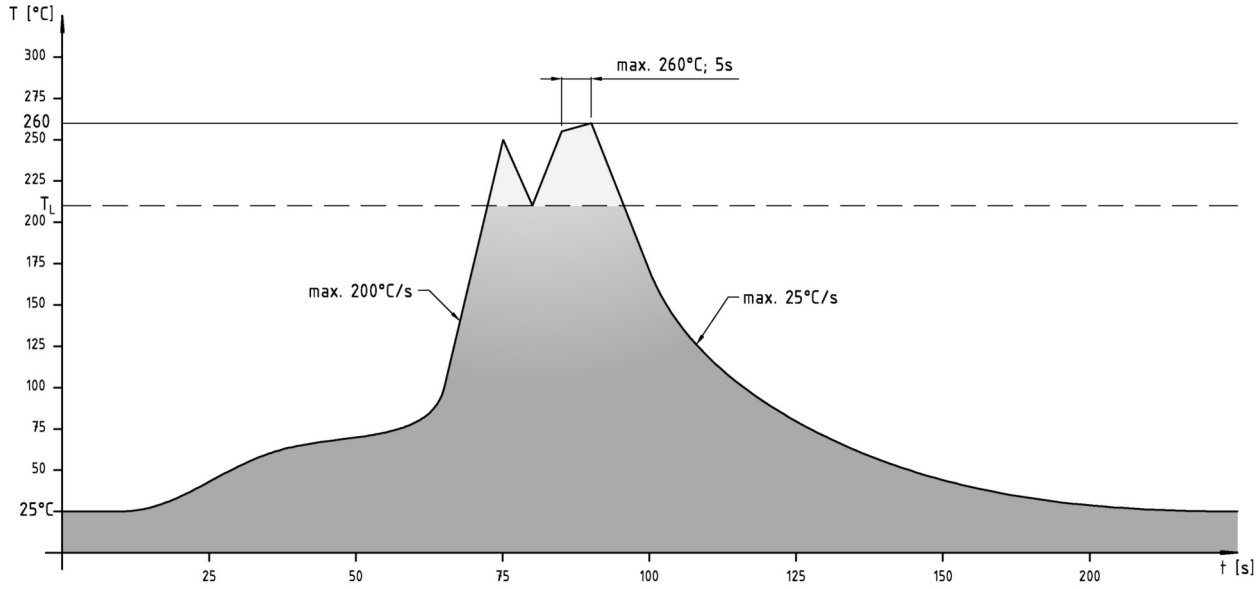


Series	*Contacts**	*Type*	*Rows**	*Plating*
W521	**03**	**3**	**1**	**50**
	02-04 Einreihig *Single row* **06/08** Zweireihig *Double row*	**3** Wannenstiftleisten gerade *Box headers straight* **4** Wannenstiftleisten gewinkelt *Box headers right-angled*	**1** Einreihig *Single row* **2** Zweireihig *Double row*	**50** Sn

* Dies ist ein **Bestellbeispiel** -
bitte durch Ihre Spezifikationen ersetzen.
** This is an **order example** -*
please replace by your specifications.

Empfehlungen für das Wellenlötverfahren

Recommendations for Wave Soldering

Die Bauteile sollten bei einer Lötbadtemperatur von 260°C in max. 5 Sekunden verlötet werden.

Empfohlenes Wellenlötprofil: